

AM2520SF4C03

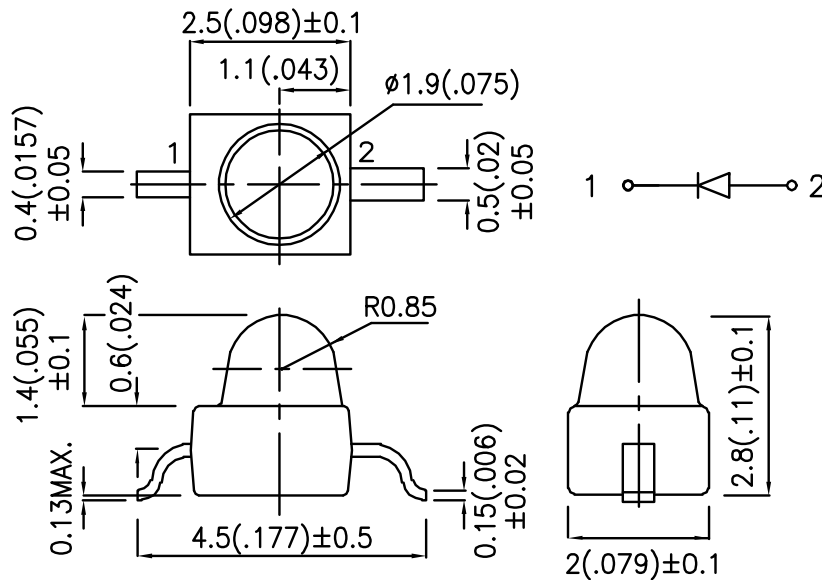
### Features

- SUBMINIA TURE PACKAGE.
- GULL WING .
- MECHANICALLY AND SPECTRALLY MATCHED TO THE PHOTOTRANSISTOR.
- PACKAGE : 1000PCS / REEL.
- RoHS COMPLIANT.

### Description

SF4 Made with Gallium Aluminum Arsenide Infrared Emitting diodes.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

## Selection Guide

Part No.	Dice	Lens Type	Po (mW/sr) @ 20mA *50mA		Viewing Angle
			Min.	Typ.	2θ1/2
AM2520SF4C03	SF4 (GaAlAs)	WATER CLEAR	1.6	4	20°
			*2.6	*8	

Notes:

- 1.θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. \* Luminous intensity with asterisk is measured at 50mA.

## Electrical / Optical Characteristics at TA=25°C

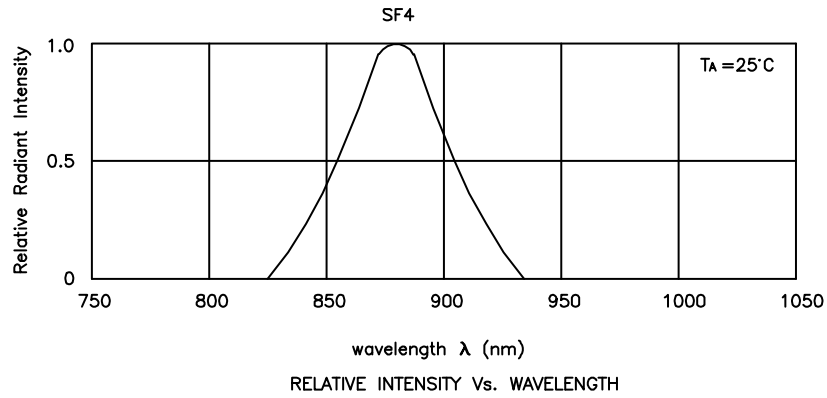
Parameter	P/N	Symbol	Typ.	Max.	Units	Test Conditions
Forward Voltage	SF4	V <sub>F</sub>	1.3	1.6	V	I <sub>F</sub> =20mA
Reverse Current	SF4	I <sub>R</sub>	-	10	uA	V <sub>R</sub> =5V
Capacitance	SF4	C	90	-	pF	V <sub>F</sub> =0V;f=1MHz
Peak Spectral Wavelength	SF4	λ <sub>P</sub>	880	-	nm	I <sub>F</sub> =20mA
Spectral Bandwidth	SF4	Δλ <sub>1/2</sub>	50	-	nm	I <sub>F</sub> =20mA

## Absolute Maximum Ratings at TA=25°C

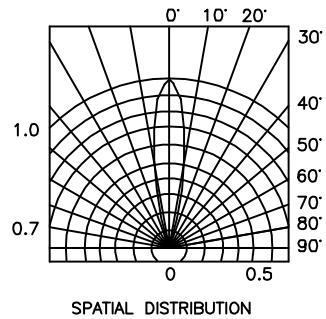
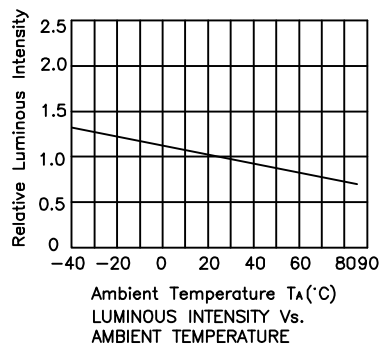
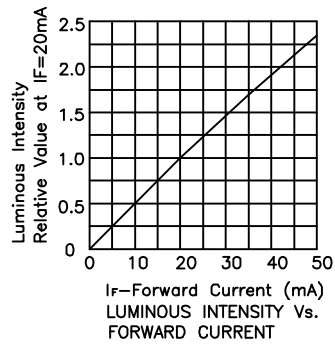
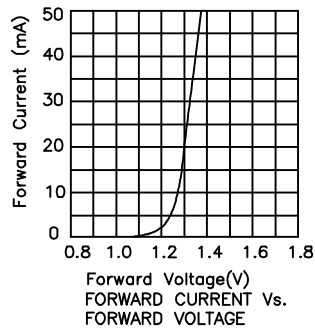
Parameter	Symbol	SF4	Units
Power Dissipation	P <sub>T</sub>	100	mW
DC Forward Current	I <sub>F</sub>	50	mA
Peak Forward Current[1]	i <sub>F</sub> S	1.2	A
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>A</sub>	-40 To +85	°C
Storage Temperature	T <sub>STG</sub>	-40 To +85	°C

Note:

1. 1/100 Duty Cycle, 10us Pulse Width.

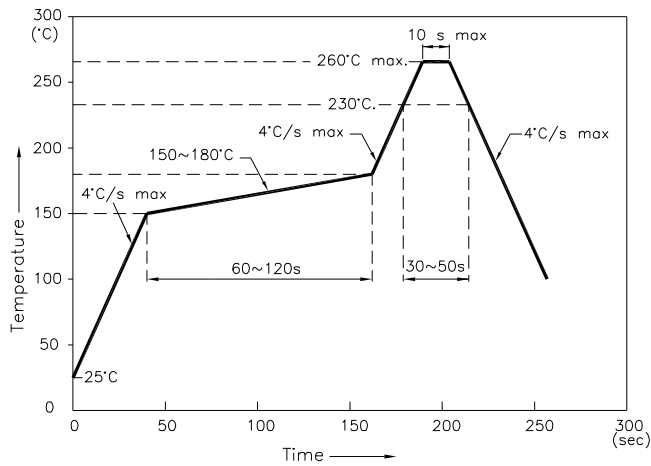


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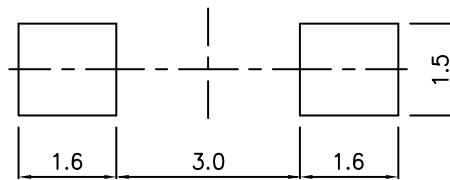
Reflow Soldering Profile For Lead-free SMT Process.



**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

